

Subst. Form PTO-1449

Docket Number (Optional)

SAM-0298

Application Number

09/994,508

INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION

Applicant

Jae-Hak Kim, et al

Filing Date

11/27/01

Group Art Unit

Not yet assigned

(Use several sheets if necessary)

## U. S. Patent Documents

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
	AL							
	AM							
	AN							
	AO							
	AP							
	AQ							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

gl	AR	Townsend, P.H., et al., "SiLK Polymer Coating with Low-Dielectric Constant and High Thermal Stability for ULSI Interlayer Dielectric," Materials Research Society Symp. Proc. Volume 476, 1997, pp. 9-17.
gl	AS	Kudo, H., et al., "Copper Dual Damascene Interconnects with Very Low-k Dielectrics Targeting for 130nm Node," IEEE, 2000, pp. 270-272.
	AT	

EXAMINER

DATE CONSIDERED

9/24/02

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy with next communication to applicant.